TECHNICAL DATASHEET

Hot melt in cartridges for edge bonding

Product:
DANAFIX 840

Date of issue: *29.04.2013*
(Replaces: 30.01.2012)

Company: *DANA LIM A/S*
Københavnsvej 220, DK-4600 Køge

Ph.: 56 64 00 70, Fax.: 56 64 00 90, www.danalim.dk
Technical Service Ph.: 56 64 00 75

Prepared by: *Laboratory, Kristian K. Pedersen*

Product description and application:

DANAFIX 840 is cartridge shaped universal edge bonding adhesive for Holz-Her machinery. The adhesive has good melting properties, good initial tack and do not tread. The delivery form is cartridges Ø 63 mm and length 80 mm. The finished material can be sawed, milled, planed, etc. immediately following bonding.

Application:

Edges:	***DANAFIX 840***
Paper:…..….............................	●
Paper (resin impregnated):.....	●
Polyester:……………………...	●
HPL:……………………………	●
PVC (pre-treated):……………	●
ABS (pre-treated):…………….	●
Melamine:.……………………	●
Venner:………………………...	●
Solid wood:.……………….......	●
Epoxy resin:………..……….	●
PP:…………………………...	

Packaging size:

Item no.	***Colour***	***Size***
6285	*Elfenben / Natur*	*15 kg (45 patroner)*
6378	*Hvid*	*15 kg (45 patroner)*

Physical / chemical properties:

	DANAFIX 840
Type:…………………………...	*EVA copolymer*
Color:…………………………...	*Natur*
Density, app.:…………………...	*1,3 g/cm^3*
Viscosity (180 °C):….………....	*110.000 cP*
Viscosity (200 °C):………..…....	*65.000 cP*
Melting point:…..…..…………..	*120±10 °C*
Heat resistance:……..………..	*+80 °C*
Cold resistance:……..…….......	*-20 °C*
Storage, cold and dry in original sealed packaging:…....	*2 years*

Direction for use:

Preparation: *The substrates for edge bonding have to be processed at precise 90° angles and should be free from dust. Boards and edges have to be conditioned to room temperature. The most favourable moisture content of the wood is 8-10%. Room temperature should not be lower than 18°C. Draughts have to be avoided.*

Application: *The amount of glue must be adjusted so that the full width of the joint contains glue. Transparent edges can be used for checking the glue spreading.*

Moisture content: *Optimum wood moisture content is 8-10 %.*

Application temperature: *200- 220 °C. For gluing of solid wood edges the temperature can shortly be set to 230 °C.*

The temperature should be checked directly at the application system. Too low temperature will result in bad adherence and too high temperature will destroy the hot melt. If the application system is not operation for a period of time the temperature must be set to 160 °C.

Safety:

Hazard Symbols: *None*
Risk and safety phrases: *None*

For further information concerning safety, refer to Safety Data Sheet.

Further information:

DANA LIM offers a range of adhesives for professionals:
100-series: Upholstering adhesives
200-series: Flooring adhesives
300-series: Wall adhesives
400-series: Wood adhesives
500-series: Sealants & PU-foams
600-series: Building-additives, fillers etc.
700-series: Paper-, packaging- and newspaper adhesives
800-series: Hot melt
900-series: Cleaning-, release agents and hardeners.

In the 800-series Hot melts DANA LIM offers:
810-serien: Hot melt sticks
840-serien: Hot melt in cartridges for edge bonding
850-serien: Hot melt for assembling
860-serien: Hot melt for profile wrapping
870-serien: Hot melt in granulate for edge bonding
880-serien: Hot melt for packaging closing
890-serien: Pressure sensitive hot melt

The information and data contained in this data sheet are based on extensive laboratory testing and our practical experiences, and are meant for helping the user to find optimum working methods. As the conditions at the user are beyond our control, we make no warranties concerning the results, achieved by the products. The information's in this technical data sheet are typical values, intended as a guideline. They should not be regarded as product specifications. Please also refer to our standard sales conditions and terms of delivery.